



**BSI Standards Publication**

## **Semiconductor devices — Micro-electromechanical devices**

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Part 27: Bond strength test for glass frit bonded structures using micro-chevron-tests (MCT)

## National foreword

This British Standard is the UK implementation of IEC 62047-27:2017.

The UK participation in its preparation was entrusted to Technical Committee EPL/47, Semiconductors.

A list of organizations represented on this committee can be obtained on request to its committee manager.

This publication does not purport to include all the necessary provisions of a contract. Users are responsible for its correct application.

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### Amendments/corrigenda issued since publication

| Date | Text affected |
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